



Final Product Change Notification

202101013F01 : QN908x Datasheet Update To Rev 1.3

Note: This notice is NXP Company Proprietary.

Issue Date: Jan 28, 2021 **Effective date:** Apr 28, 2021

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Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input checked="" type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware <input type="checkbox"/> Other				

PCN Overview

Description

NXP Semiconductors announces that QN908x Datasheet has been updated to revision 1.3. The revision history included in the updated document provides a detailed description of the changes:

1. Updated the peak power to 1.6 mW in Section 2 ?General description?
2. Added IIN in Table 18.
3. Updated HVQFN48-pin package outline in Figure 20

The updated QN908x Datasheet can be found at:

https://www.nxp.com/products/wireless/bluetooth-low-energy/qn908x-ultra-low-power-bluetooth-low-energy-system-on-chip-solution:QN9080?tab=Documentation_Tab

Reason

The Datasheet have been updated to provide additional technical clarification on some device features and package outline.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Not Applicable

Production

Planned first shipment May 01, 2021

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Max package thickness in package outline change from 0.9mm to 1mm, no other impact.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Feb 27, 2021.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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Affected Part Numbers

QN9080DHNY

QN9080DHNE

QN9080CHNY